For immediate release

TAIYO YUDEN Mobile Technology Co., Ltd.,
Establishment of a New Factory

Responding to Further Expansion in Market for Communication Devices

TOKYO, July 30, 2013 — TAIYO YUDEN Mobile Technology Co., Ltd., a subsidiary of TAIYO YUDEN CO., LTD., will purchase a portion of the land and building in Ome, Tokyo held by Hitachi, Ltd., and establish a new factory. The timing for this purchase is April 2014.

The key products of TAIYO YUDEN Mobile Technology are SAW/FBAR devices for mobile communication and front-end modules (Notes: 1, 2, and 3). In recent years demand for communication devices has been increasing due to the widespread use and growth of mobile equipment, including smartphones, as well as an increase in communications bands needed to support these communication devices. The Company anticipates further expansion in this market and is compelled to address this expansion by making the acquisition. The Company will establish the new factory and bolster its efforts to increase production capabilities and further enhance the critical customer service levels it offers.

Image of the completed factory

Since joining the TAIYO YUDEN group in 2010, TAIYO YUDEN Mobile Technology has seen increases in demand for its communication device products and has been successful in expanding its business. In 2011 the Company established its Tokorozawa Plant (Iruma-gun, Saitama Prefecture) and, in combination with its existing Suzaka Plant, has worked to provide a stable, uninterrupted supply to the rapidly growing smartphone market.

At present, demand for communication devises is rapidly expanding and a further increase in demand is anticipated accompanying an increase in communication methods and enhanced communication speeds as well as an expansion of the smartphone market. As a response to these market dynamics and to customer demand, TAIYO YUDEN Mobile Technology decided to acquire the land and building and establish a new factory. This will give the Company the ability to expand production and put in place a structure which will be able to speedily respond to heightened supply responsibilities with the additional wherewithal to address stepped-up capacity requirements. The

size of the land for the new factory will be approximately 1.5 times the size of the Suzaka Plant. The Company believes it will be able to achieve a further expansion in its production capability, enhancements in production efficiency and improvement in quality. By these actions, the Company will put itself in a position to firmly absorb demand for communication devices, which is in line with its objectives set forth in the TAIYO YUDEN group's medium-term management plan. The plan reaches its final year in the fiscal year ending in March 2015.

It is the Company's intention to conclude the real estate sale agreement with Hitachi on July 31, 2013 and to acquire the land and building on April 1, 2014. The Company will gradually ramp-up production focusing on new products.

【Overview of TAIYO YUDEN Mobile Technology Co., Ltd.】

(1) Corporate name	TAIYO YUDEN Mobile Technology Co., Ltd.
(2) Representative	Yuji Ikeda, President and CEO
(3) Location	Shin-Yokohama Square Bldg., 2-3-12, Shin-Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa, Japan
(4) Established	March, 2010
(5) Capitalization	Wholly owned subsidiary of TAIYO YUDEN CO., LTD.
(6) Main business	Manufacturing of SAW/FBAR Devices for Mobile Communication and Frond-end Modules
(7) Number of employees	557 (as of March, 2013)

【Overview of TAIYO YUDEN Mobile Technology's New Factory】

(1) Location	6-16-3, Shinmachi, Ome-shi, Tokyo, Japan
(2) Main products	SAW/FBAR Devices for Mobile Communication and Frond-end Modules
(3) Ground area	56,000 ㎡
(4) Floor area	53,000 ㎡

[Glossary]

(Note 1) SAW (Surface Acoustic Wave)

Acoustic wave which travels along the surface of a material. The SAW filter uses the surface elasticity of the piezoelectric body.

(Note 2) FBAR (Film Bulk Acoustic Resonator)

One of the BAW (Bulk Acoustic Wave) filters which use a bulk wave which is the resonant oscillation of the piezoelectric membrane; a film type piezoelectric membrane sandwiched between electrodes is used.

(Note 3) Front-end Module

A product which integrates the required circuits as one module in the reception portion of the antenna.